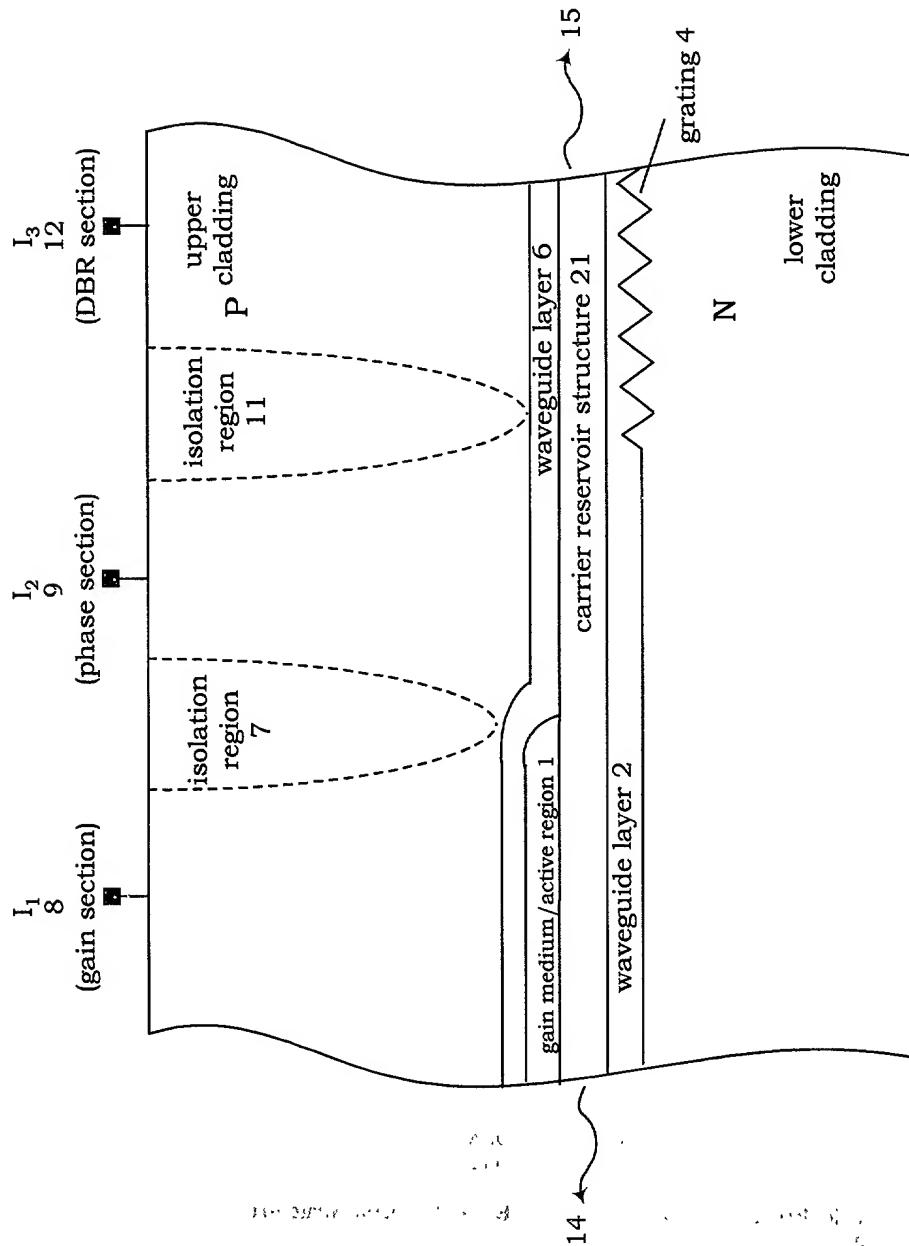


FIG. 1

FIG. 2



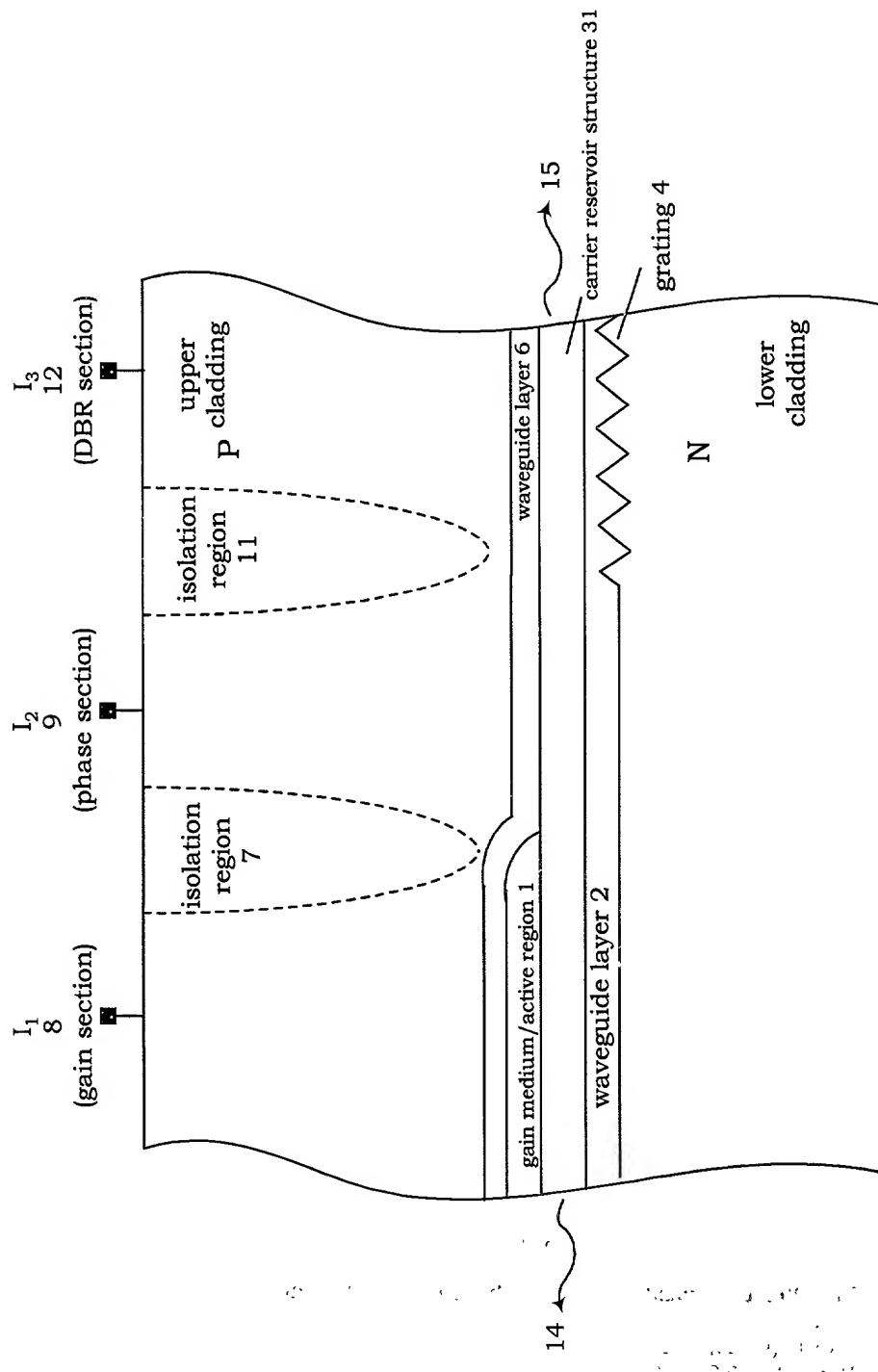


FIG. 3

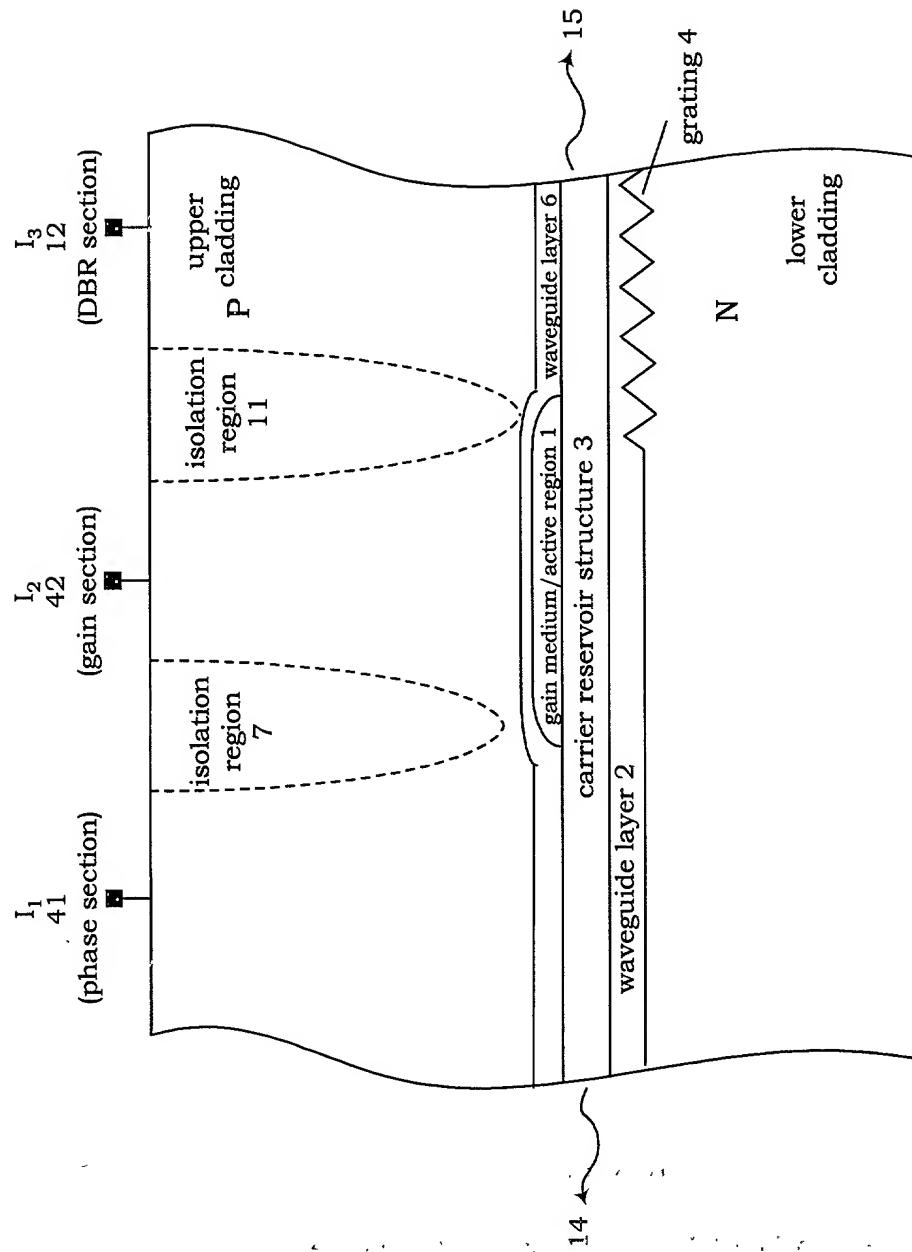


FIG. 4

FIG. 5

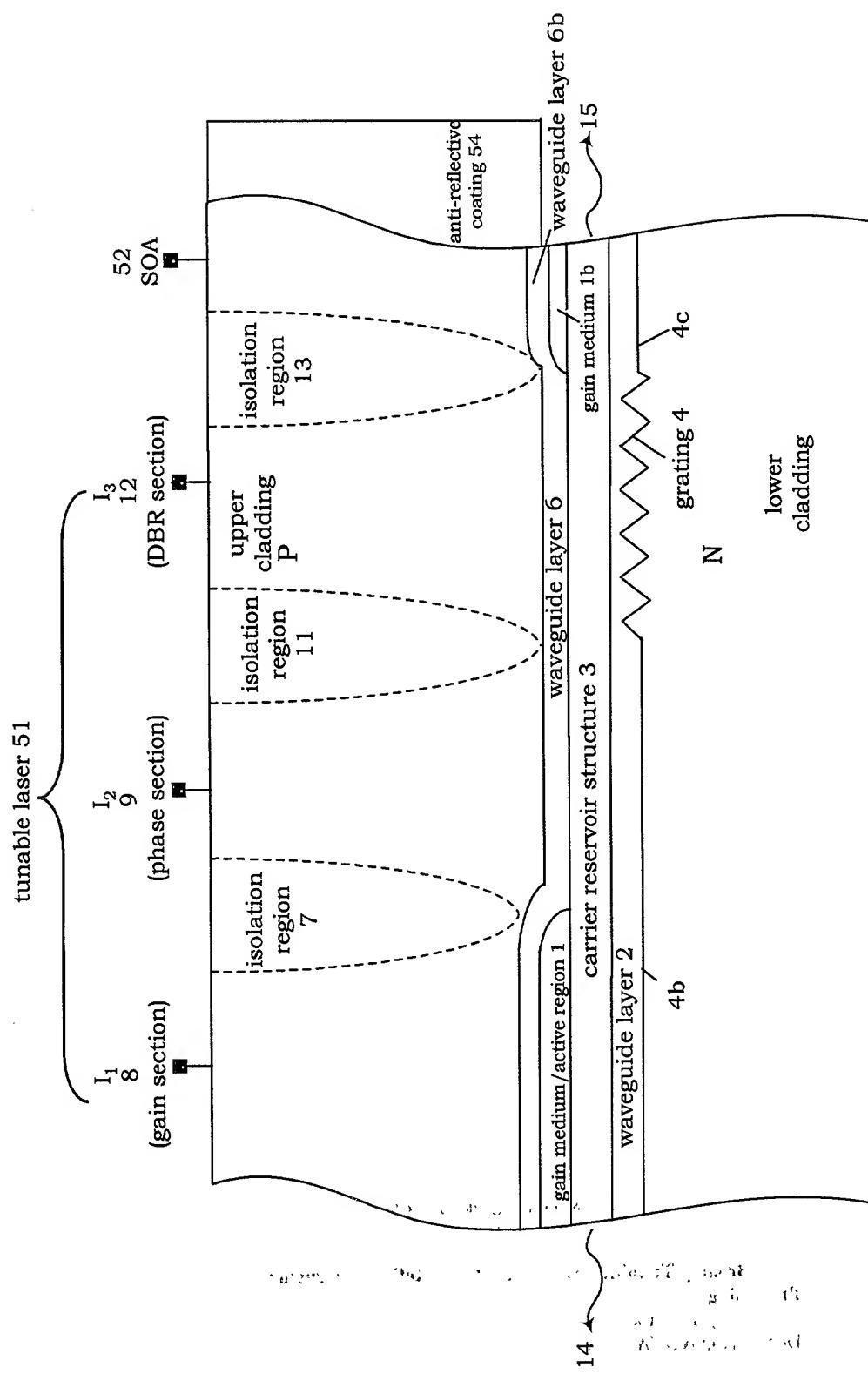
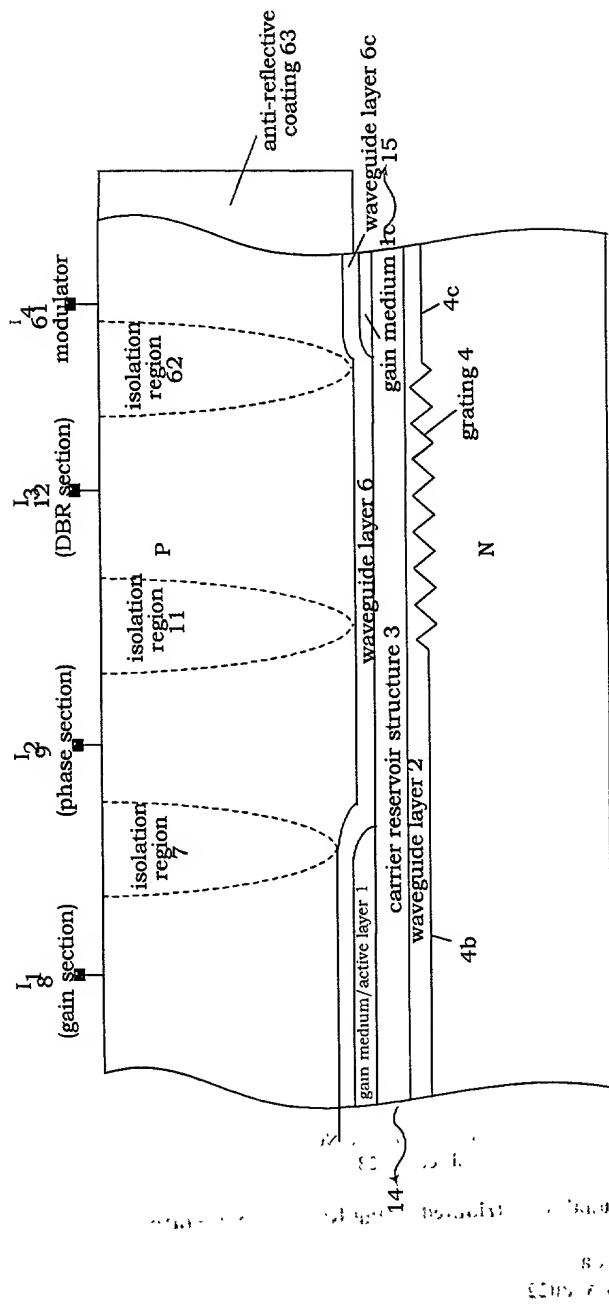


FIG. 6

60



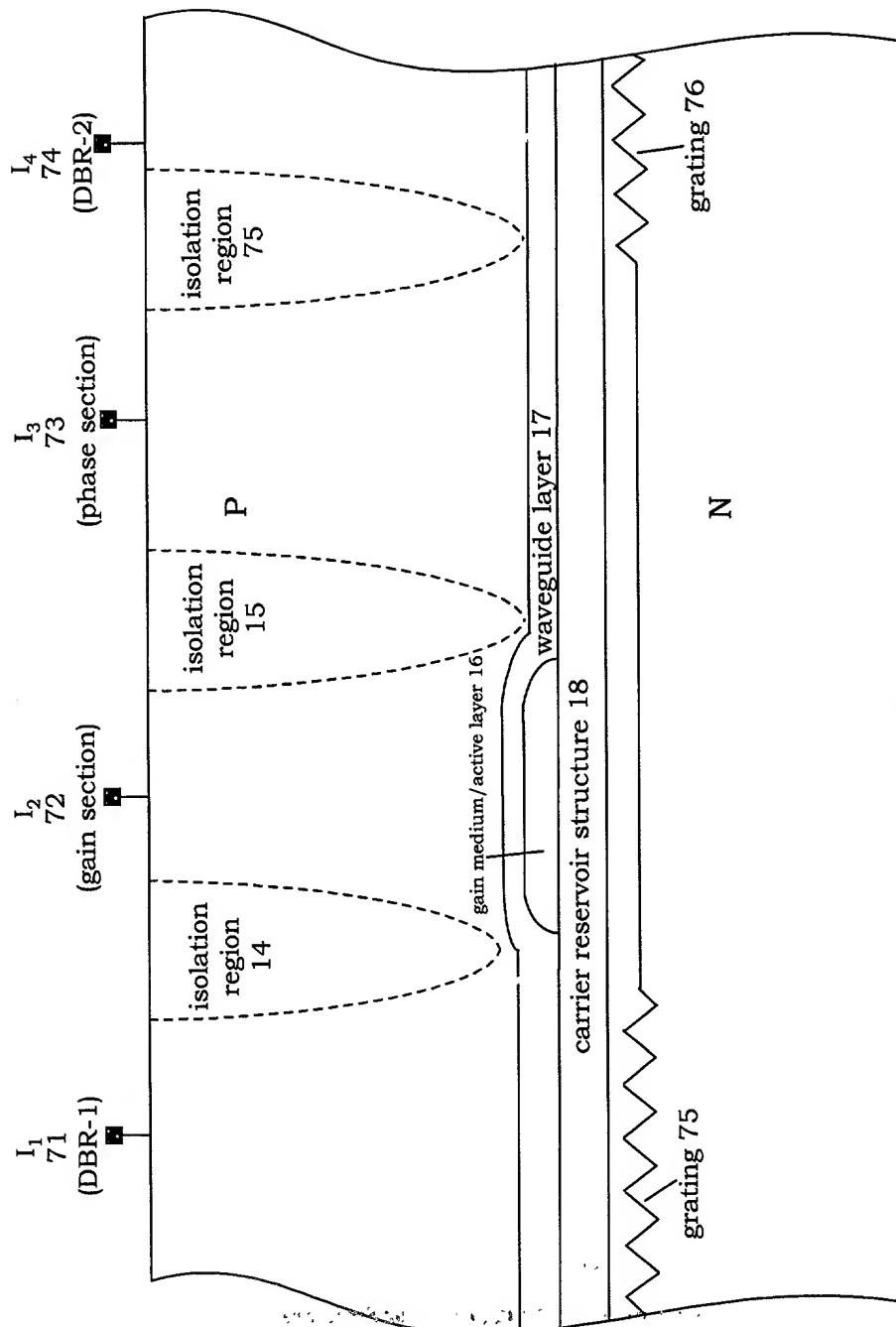


FIG. 7

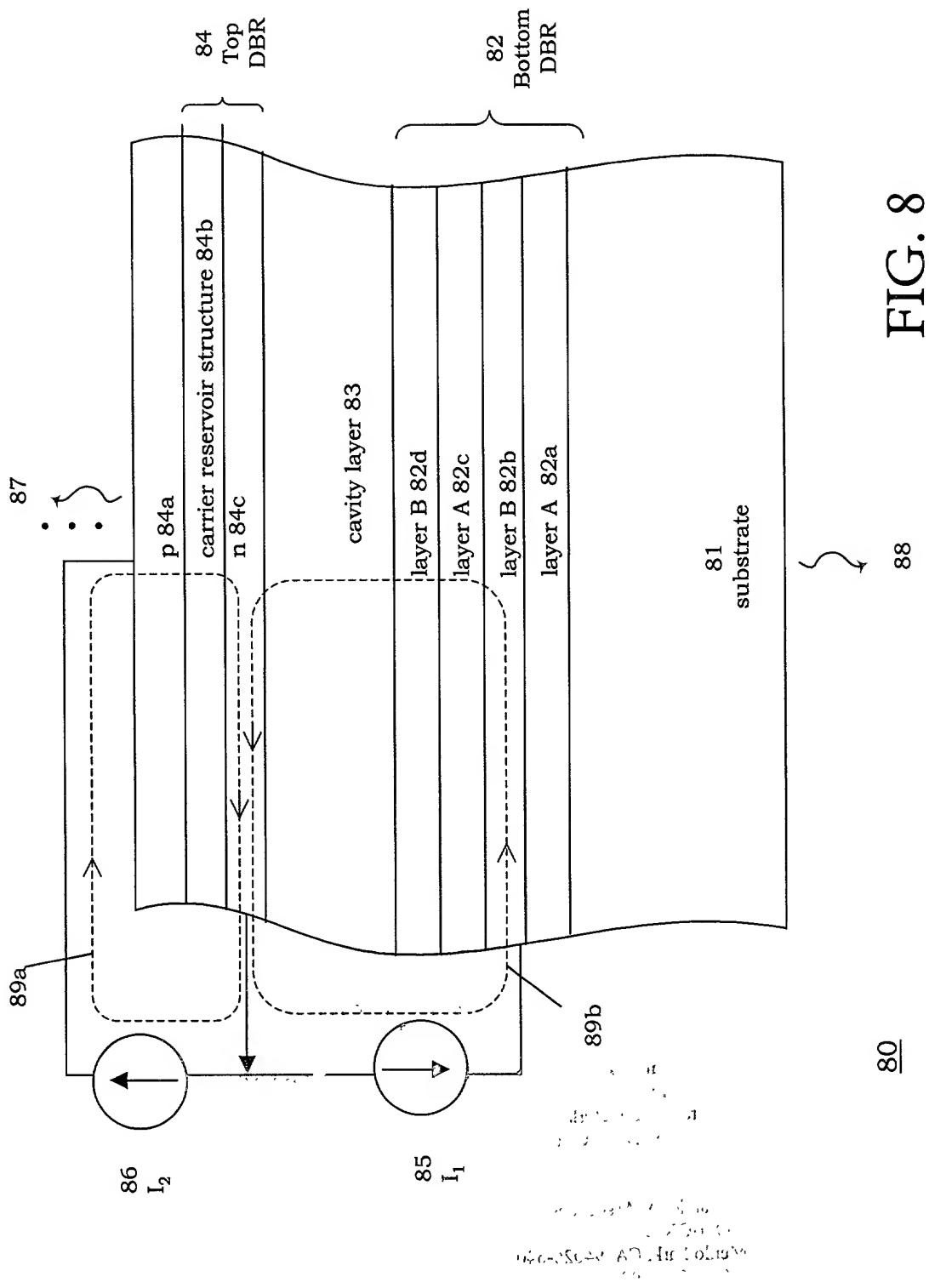
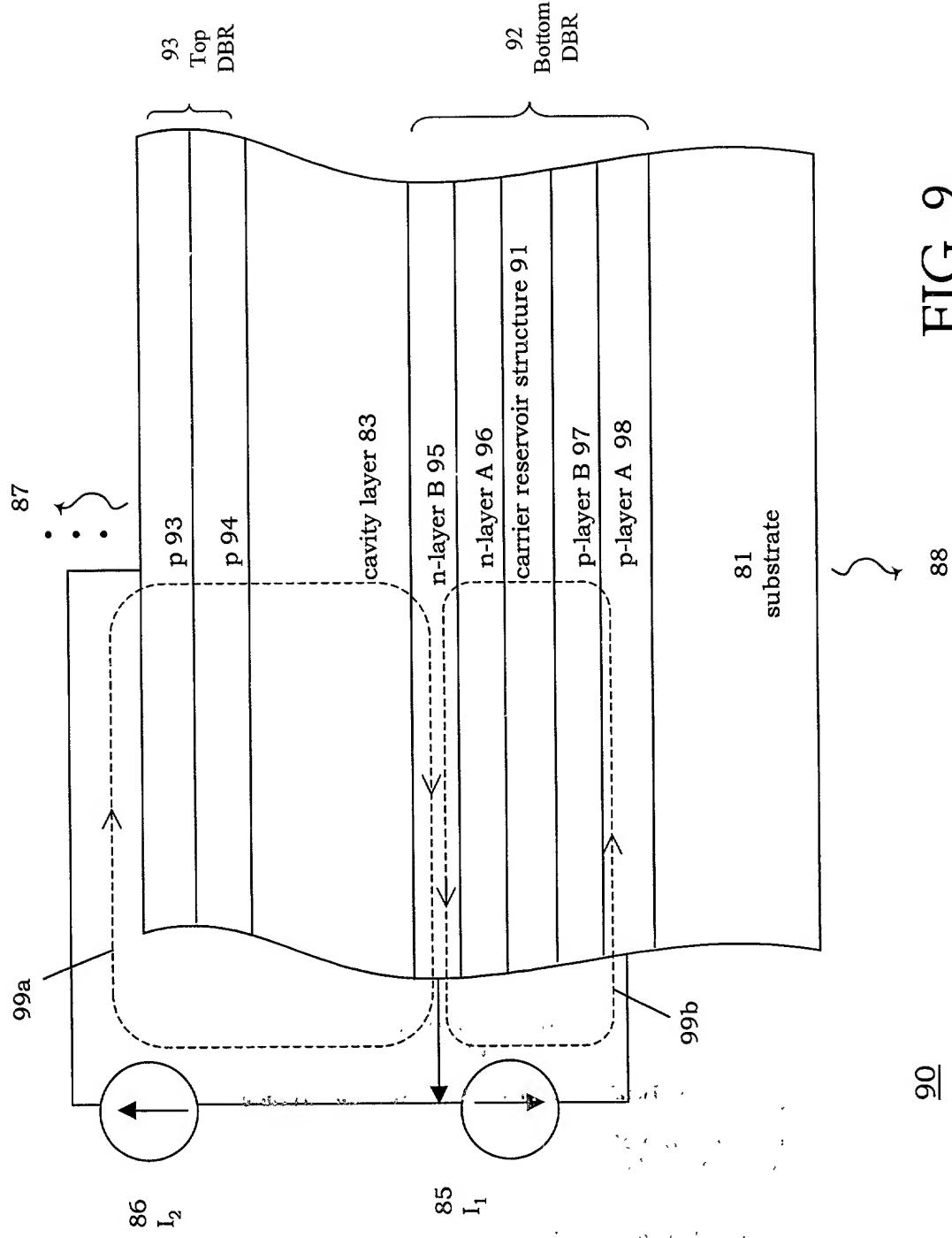


FIG. 8



90

88

FIG. 9

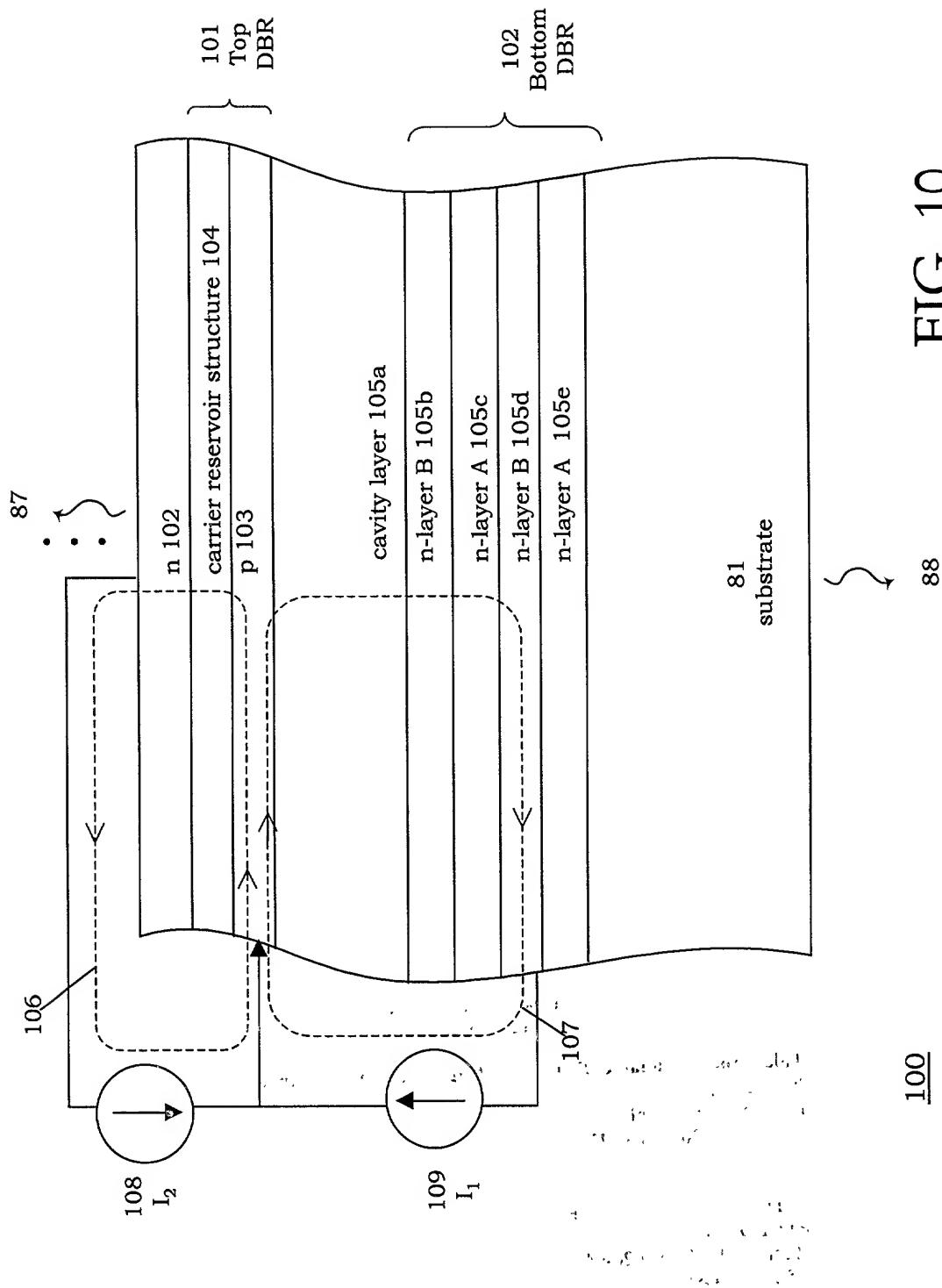


FIG. 10

100

88

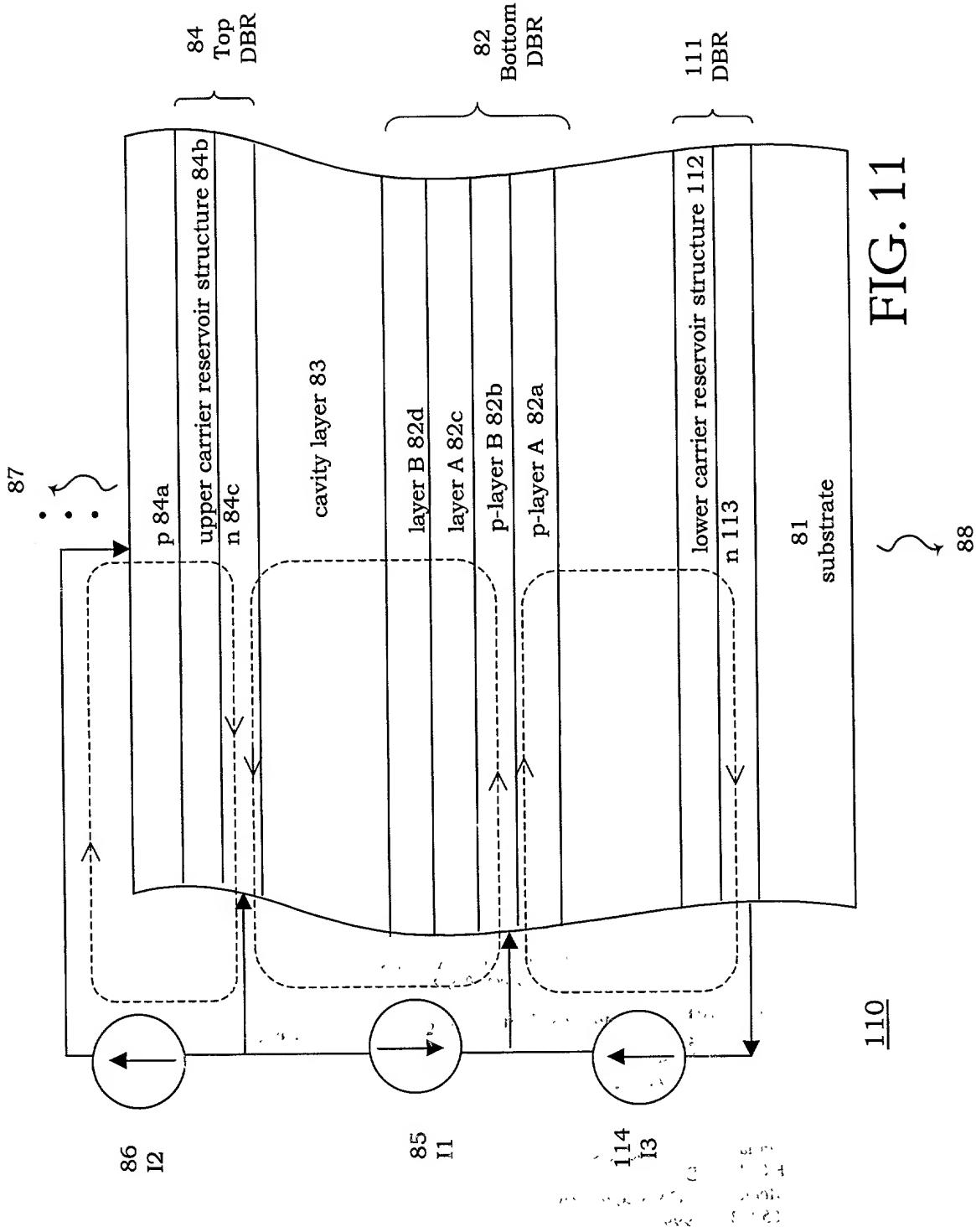


FIG. 11

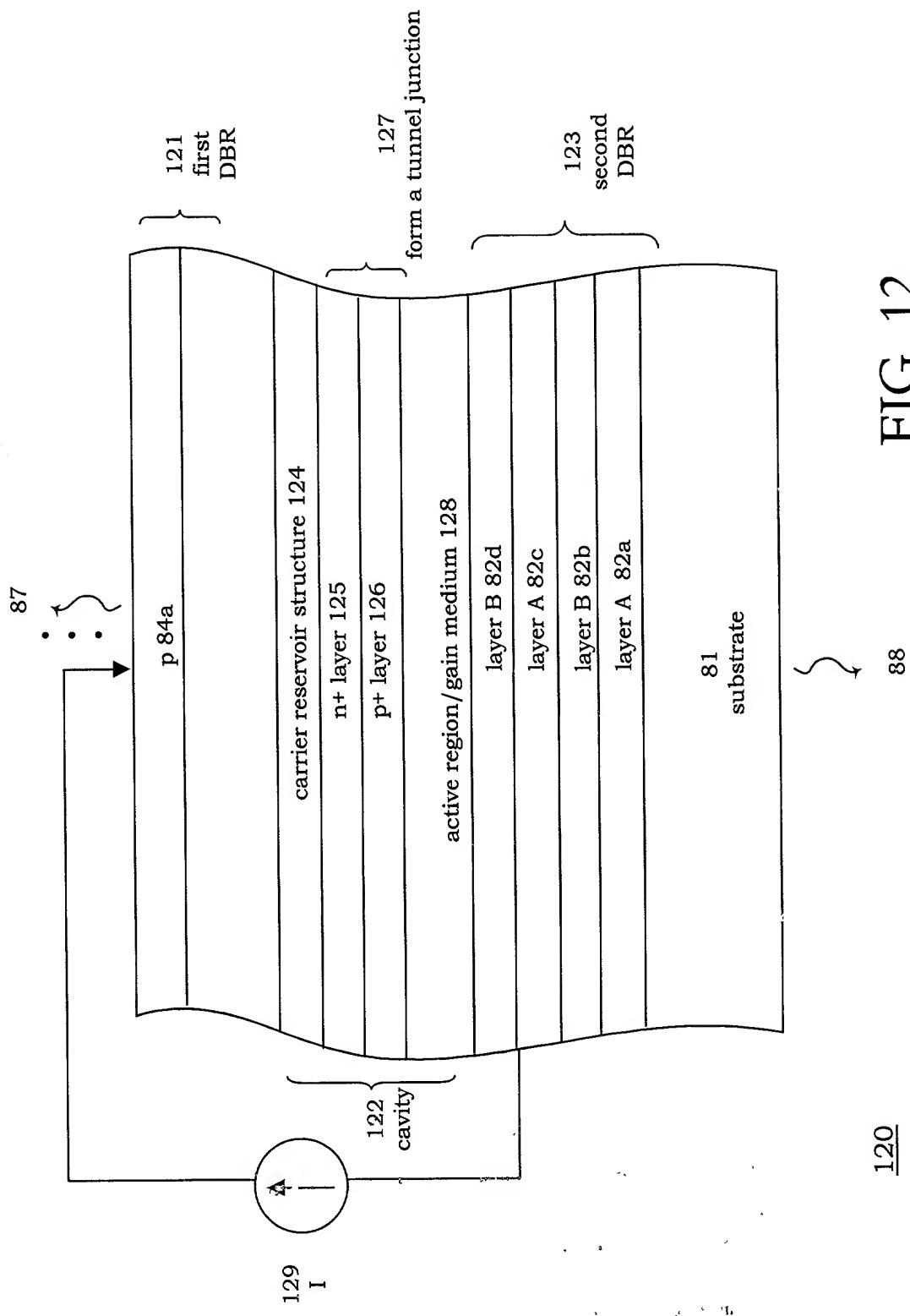
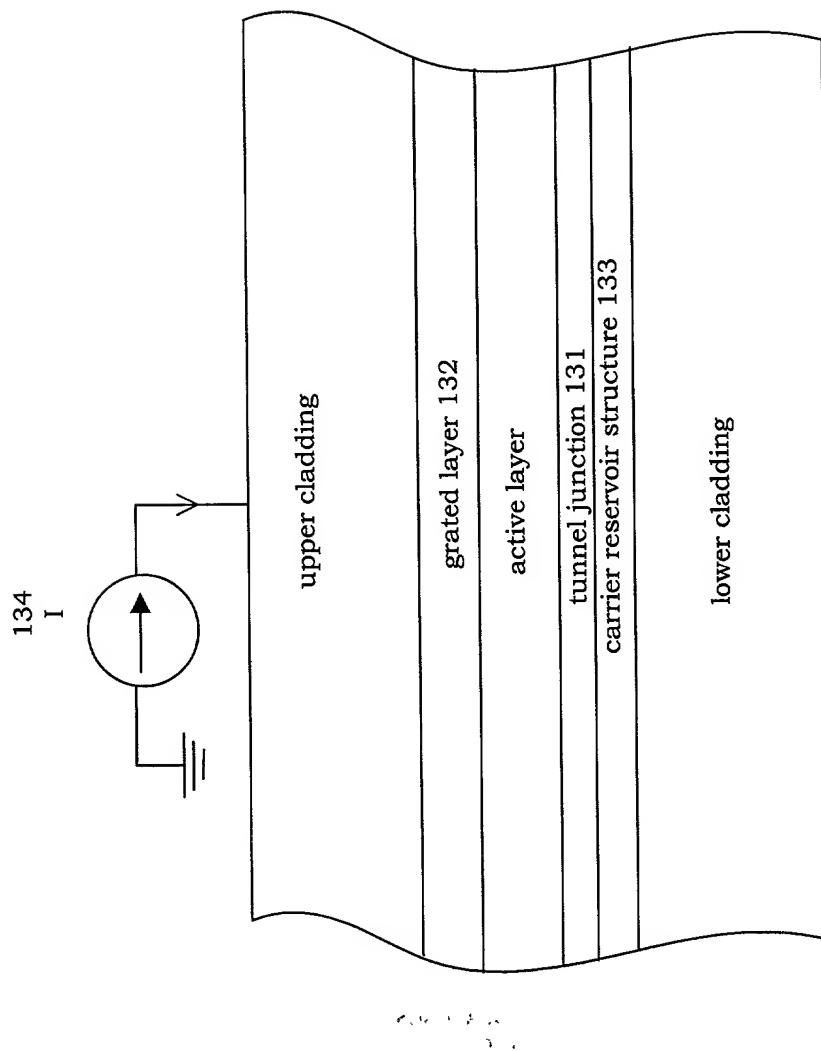


FIG. 12



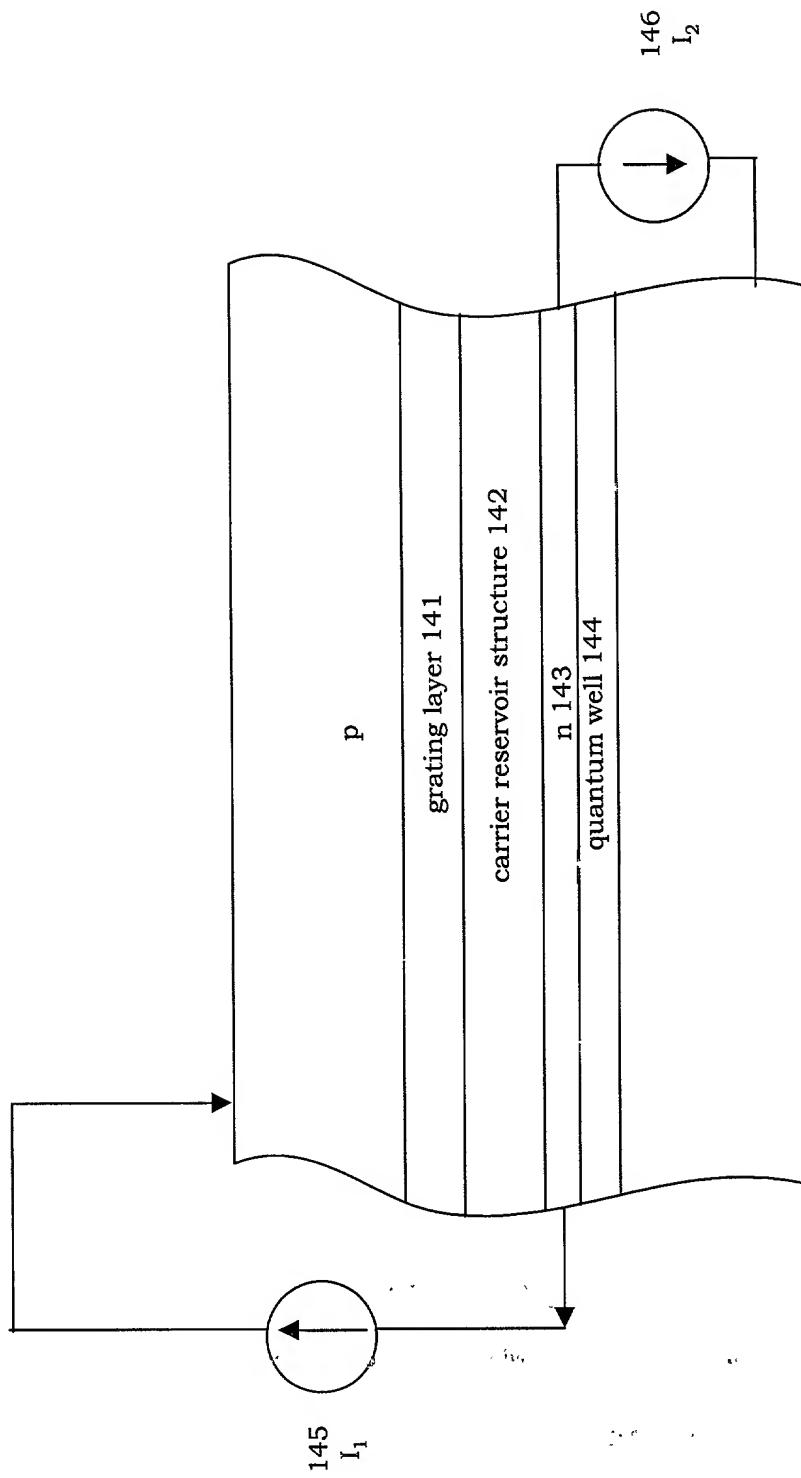


FIG. 14

140

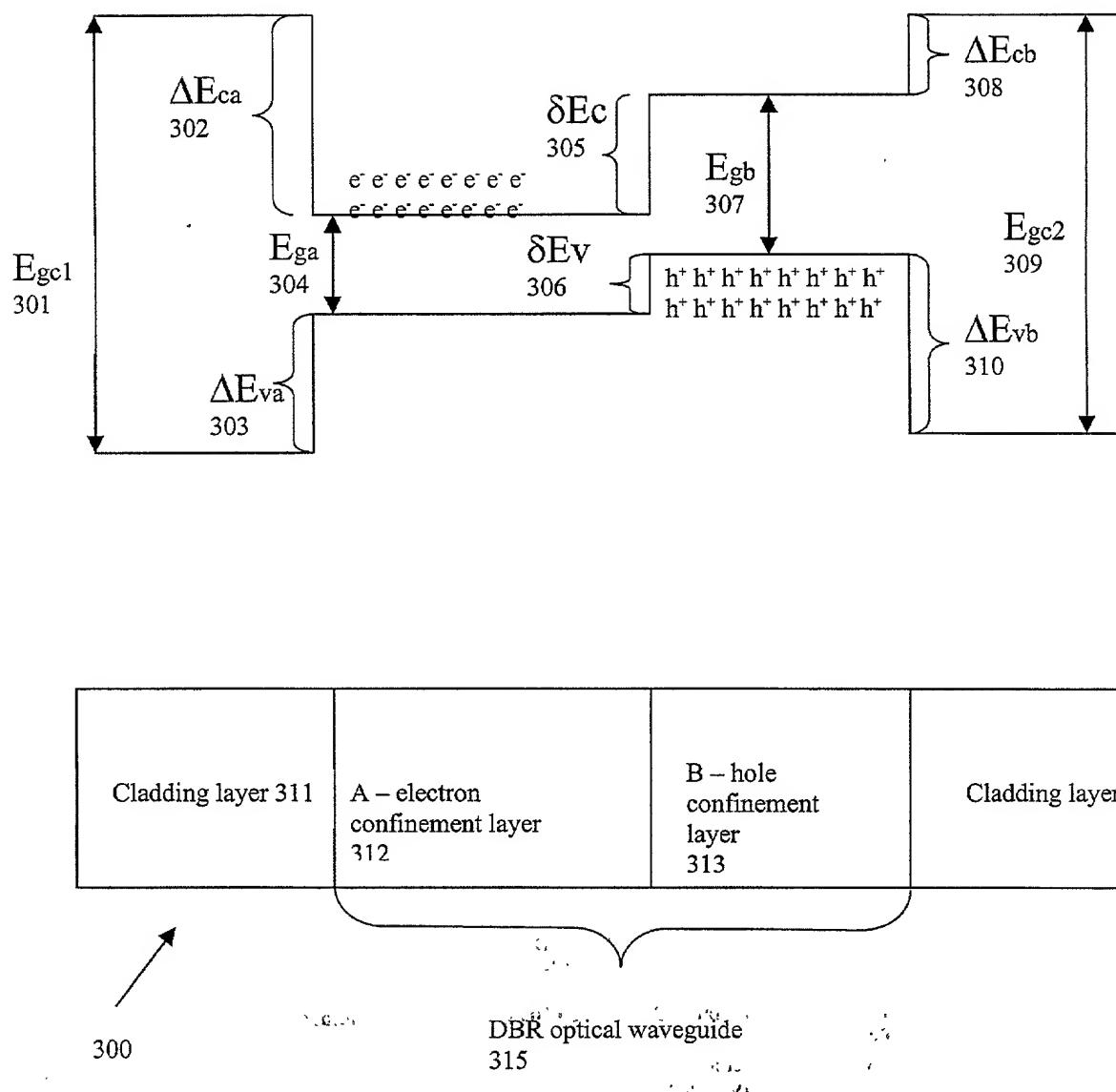


FIG. 15

U.S. GOVERNMENT WORK

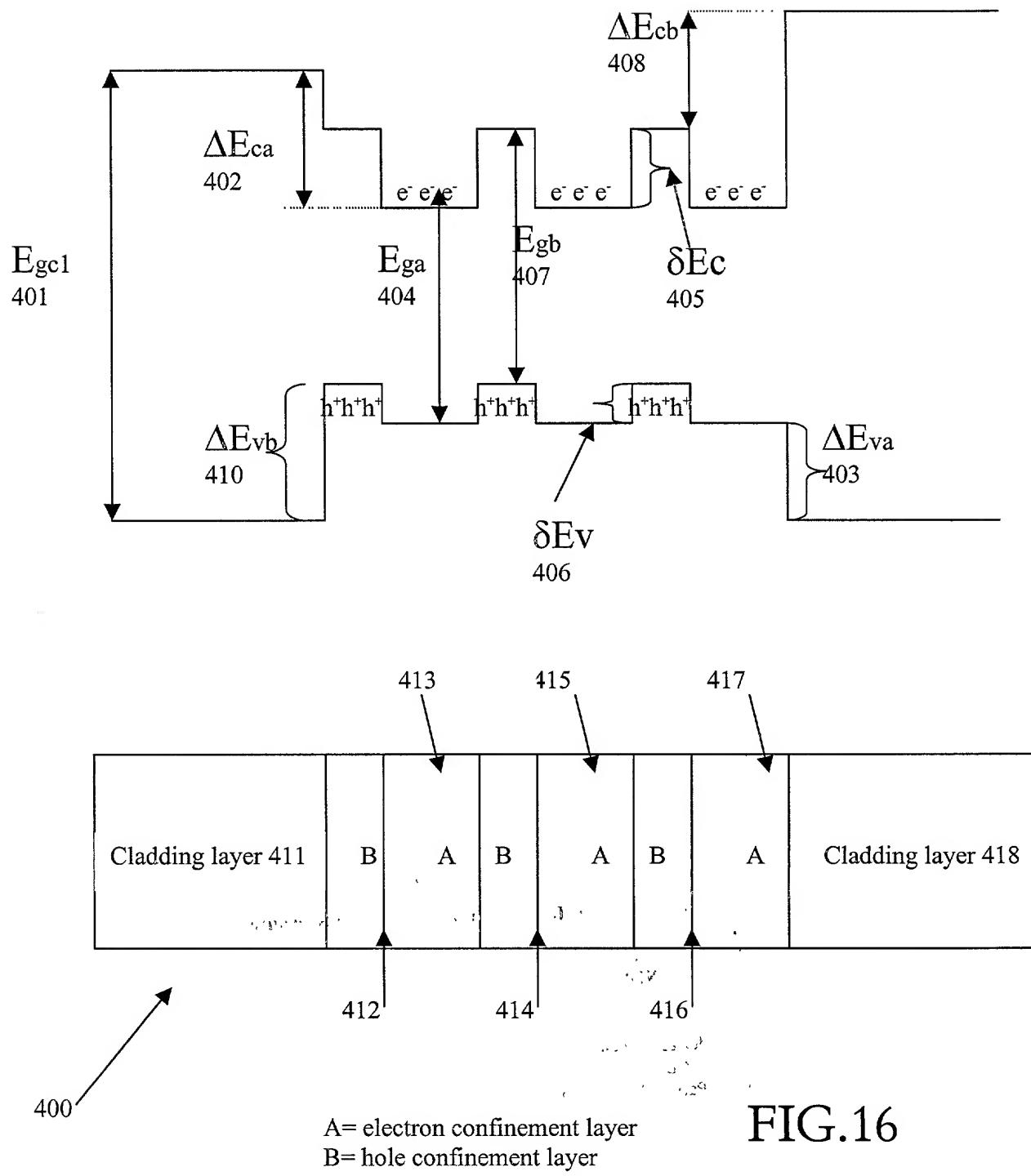
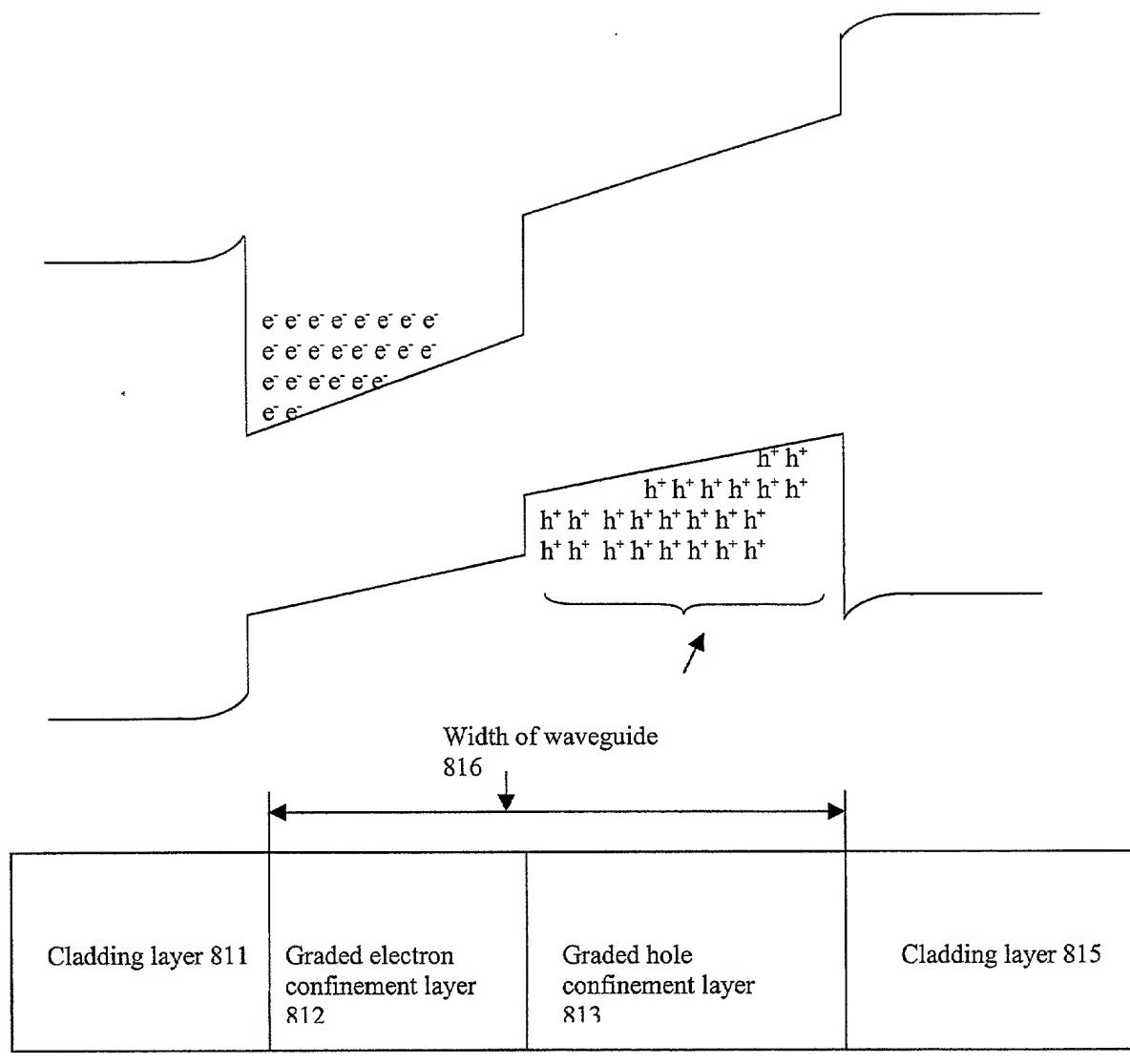
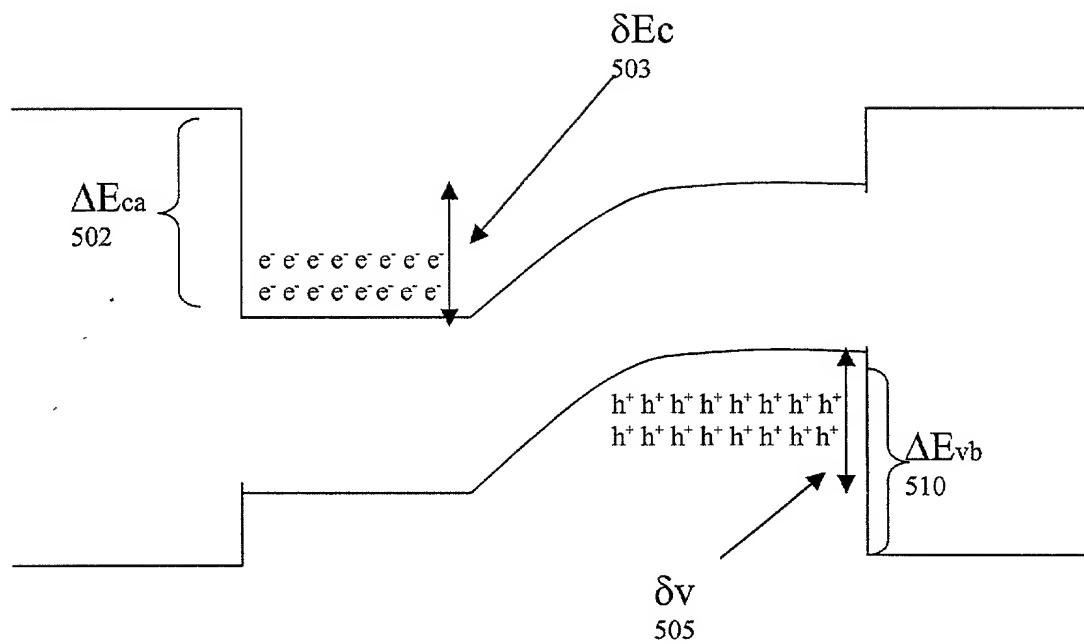


FIG.16



800

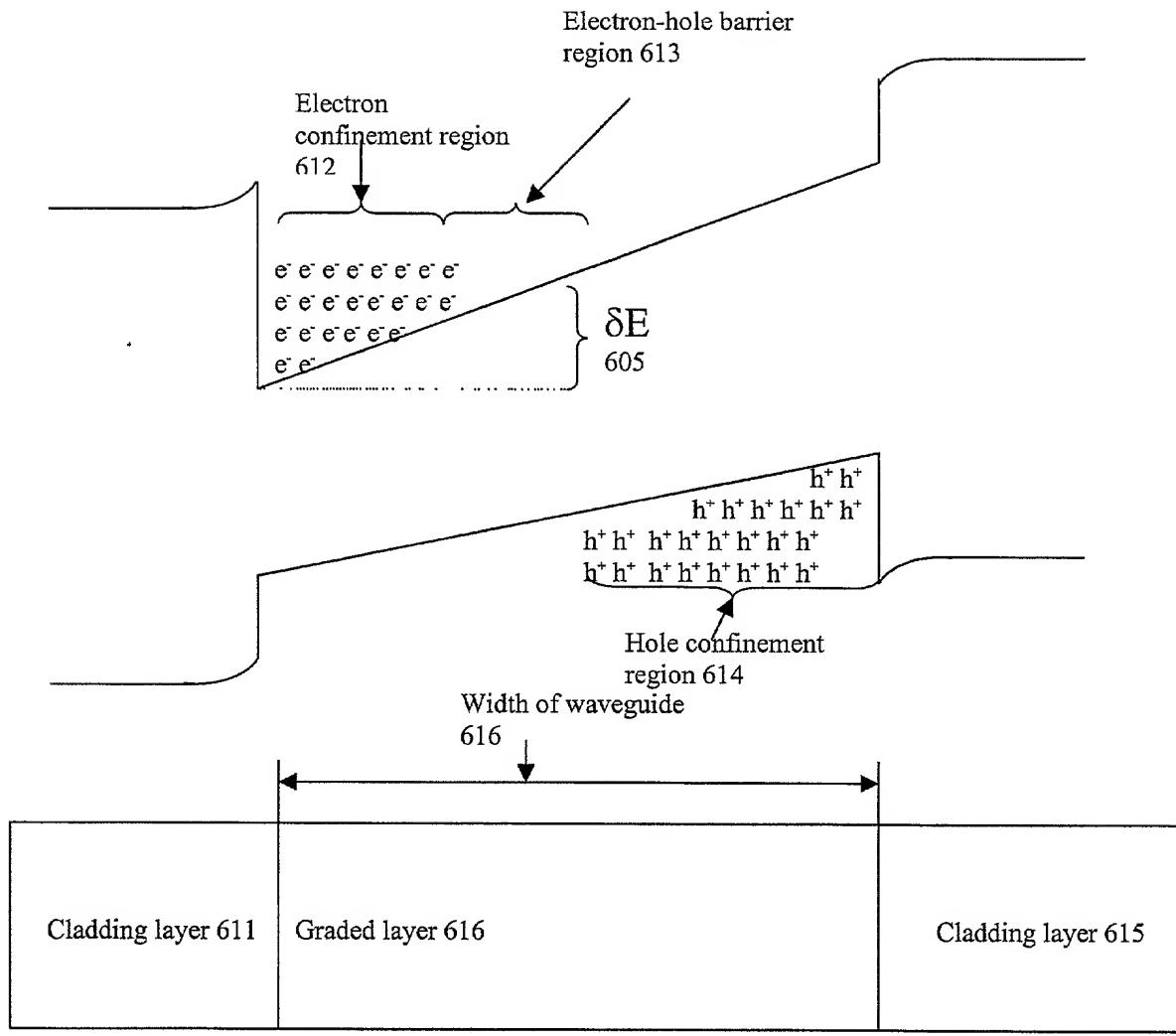
FIG. 17



|                    |                                    |                           |                                |                    |
|--------------------|------------------------------------|---------------------------|--------------------------------|--------------------|
| Cladding layer 511 | A – electron confinement layer 512 | Graded layer 513<br>A → B | B - hole confinement layer 514 | Cladding layer 515 |
|--------------------|------------------------------------|---------------------------|--------------------------------|--------------------|

500

FIG. 18



600

FIG. 19

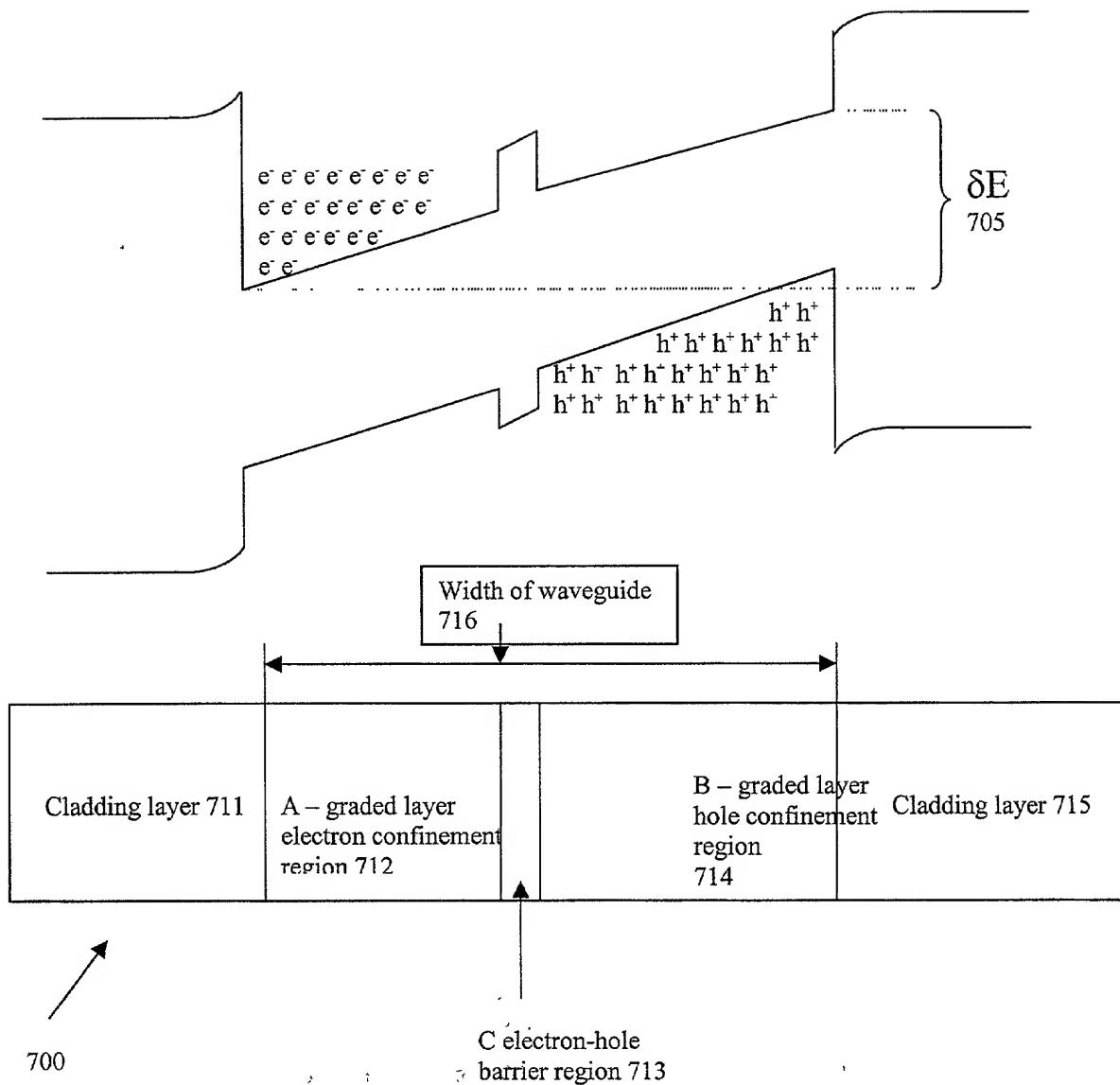


FIG. 20

885

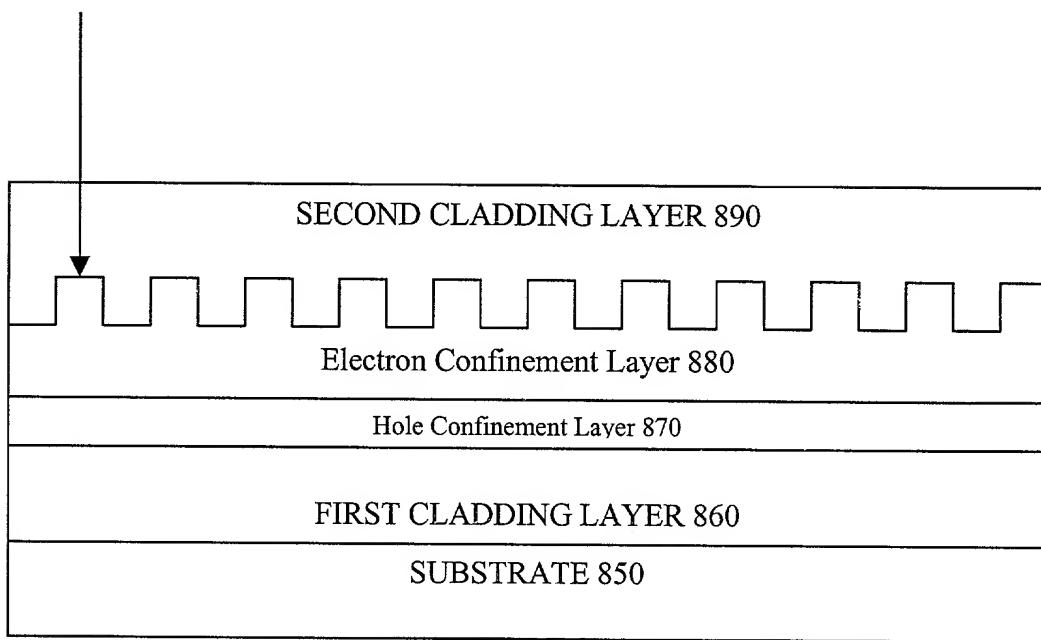


FIG. 21

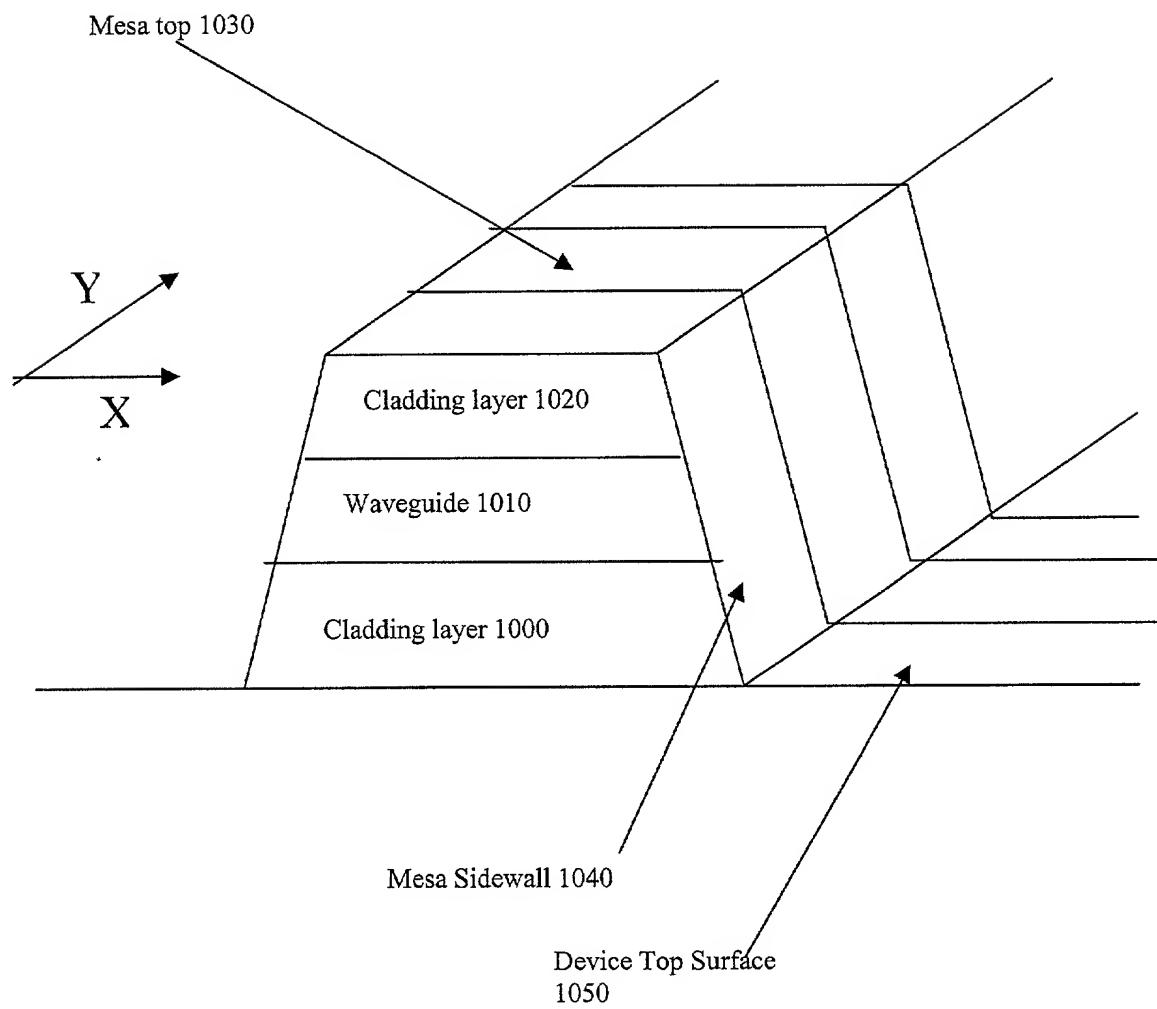
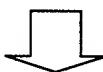
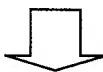


FIG. 22

Create a first cladding layer (Step 910).



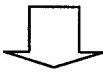
Create a grating layer (Step 920).



Create a hole confinement region layer (Step 930).



Create an electron confinement region layer (Step 940).



Create a second cladding layer (Step 950).



(Optional) Pattern laser structure and additional device processing (Step 960).

FIG. 23